

FEATURES

- 10µs Short Circuit Withstand
- High Thermal Cycling Capability
- Soft Punch Through Silicon
- Isolated AISiC Base with AlN Substrates
- 9.5kV Internal Isolation
- Lead Free construction

APPLICATIONS

- High Reliability Inverters
- Motor Controllers
- Traction Drives
- Choppers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 1200V to 6500V and currents up to 2400A.

The DIM400GDM33-F032 is a single switch 3300V, n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10µs short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DIM400GDM33-F032

Note: When ordering, please use the complete part number

KEY PARAMETERS

| | |
|-----------------------|--------------|
| V_{CES} | 3300V |
| $V_{CE(sat)}$ * (typ) | 2.8V |
| I_C (max) | 400A |
| $I_{C(PK)}$ (max) | 800A |

* Measured at the auxiliary terminals

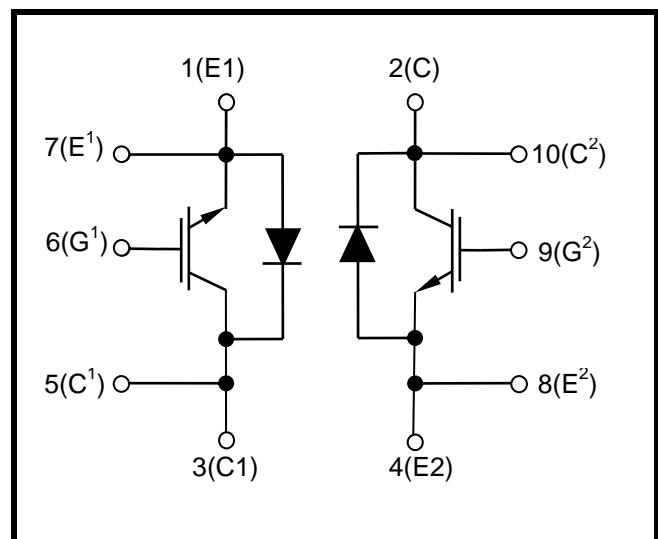


Fig. 1 Circuit configuration



Fig. 2 Package

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{case} = 25^{\circ}\text{C}$ unless stated otherwise

| Symbol | Parameter | Test Conditions | Max. | Units |
|--------------|-----------------------------------|---|----------|-----------------------|
| V_{CES} | Collector-emitter voltage | $V_{GE} = 0\text{V}$ | 3300 | V |
| V_{GES} | Gate-emitter voltage | | ± 20 | V |
| I_C | Continuous collector current | $T_{case} = 90^{\circ}\text{C}$ | 400 | A |
| $I_{C(PK)}$ | Peak collector current | 1ms, $T_{case} = 115^{\circ}\text{C}$ | 800 | A |
| P_{max} | Max. transistor power dissipation | $T_{case} = 25^{\circ}\text{C}$, $T_j = 150^{\circ}\text{C}$ | 5.2 | kW |
| I^2t | Diode I^2t value | $V_R = 0$, $t_p = 10\text{ms}$, $T_j = 125^{\circ}\text{C}$ | 80 | kA^2s |
| V_{isol}^* | Isolation voltage – per module | Commoned terminals to base plate. AC RMS, 1 min, 50Hz | 9500 | V |
| Q_{PD} | Partial discharge – per module | IEC1287, $V_1 = 6400\text{V}$, $V_2 = 4700\text{V}$, 50Hz RMS | 10 | pC |

* Package external clearances may not conform to all 9.5kV isolation standards.
Minimum external creepage/clearance distance between terminals and base plate is 33mm

THERMAL AND MECHANICAL RATINGS

| | |
|-----------------------------------|-------|
| Internal insulation material: | AlN |
| Baseplate material: | AlSiC |
| Creepage distance: | 33mm |
| Clearance: | 20mm |
| CTI (Comparative Tracking Index): | 350 |

| Symbol | Parameter | Test Conditions | Min | Typ. | Max | Units |
|---------------|---|---|-----|------|-----|------------------------------|
| $R_{th(j-c)}$ | Thermal resistance – transistor | Continuous dissipation - junction to case | - | - | 24 | $^{\circ}\text{C}/\text{kW}$ |
| $R_{th(j-c)}$ | Thermal resistance – diode | Continuous dissipation - junction to case | - | - | 48 | $^{\circ}\text{C}/\text{kW}$ |
| $R_{th(c-h)}$ | Thermal resistance – case to heatsink (per module) | Mounting torque 5Nm (with mounting grease) | - | - | 8 | $^{\circ}\text{C}/\text{kW}$ |
| T_j | Junction temperature | Transistor | - | - | 150 | $^{\circ}\text{C}$ |
| | | Diode | - | - | 125 | $^{\circ}\text{C}$ |
| T_{stg} | Storage temperature range | - | -40 | - | 125 | $^{\circ}\text{C}$ |
| | Screw torque | Mounting – M6 | - | - | 5 | Nm |
| | | Electrical connections – M4 | - | - | 2 | Nm |
| | | Electrical connections – M8 | - | - | 10 | Nm |

ELECTRICAL CHARACTERISTICS
 $T_{case} = 25^{\circ}C$ unless stated otherwise.

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|-------------------------|--------------------------------------|--|-----|------|-----|-------------|
| I_{CES} | Collector cut-off current | $V_{GE} = 0V, V_{CE} = V_{CES}$ | | | 2 | mA |
| | | $V_{GE} = 0V, V_{CE} = V_{CES}, T_{case} = 125^{\circ}C$ | | | 30 | mA |
| I_{GES} | Gate leakage current | $V_{GE} = \pm 20V, V_{CE} = 0V$ | | | 1 | μA |
| $V_{GE(TH)}$ | Gate threshold voltage | $I_C = 40mA, V_{GE} = V_{CE}$ | 5.5 | 6.5 | 7.0 | V |
| $V_{CE(sat)}^{\dagger}$ | Collector-emitter saturation voltage | $V_{GE} = 15V, I_C = 400A$ | | 2.8 | | V |
| | | $V_{GE} = 15V, I_C = 400A, T_j = 125^{\circ}C$ | | 3.6 | | V |
| I_F | Diode forward current | DC | | 400 | | A |
| I_{FM} | Diode maximum forward current | $t_p = 1ms$ | | 800 | | A |
| V_F^{\dagger} | Diode forward voltage | $I_F = 400A$ | | 2.9 | | V |
| | | $I_F = 400A, T_j = 125^{\circ}C$ | | 3.0 | | V |
| C_{ies} | Input capacitance | $V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$ | | 72 | | nF |
| Q_g | Gate charge | $\pm 15V$ | | 10 | | μC |
| C_{res} | Reverse transfer capacitance | $V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$ | | 1.1 | | nF |
| L_M | Module inductance | | | 25 | | nH |
| R_{INT} | Internal transistor resistance | | | 260 | | $\mu\Omega$ |
| SC_{Data} | Short circuit current, I_{SC} | $T_j = 125^{\circ}C, V_{CC} = 2500V$ $t_p \leq 10\mu s, V_{GE} \leq 15V$ $V_{CE(max)} = V_{CES} - L^* \times di/dt$ IEC 60747-9 | | 1850 | | A |

Note:
 \dagger Measured at the power busbars, not the auxiliary terminals

 $*$ L is the circuit inductance + L_M

ELECTRICAL CHARACTERISTICS

$T_{\text{case}} = 25^{\circ}\text{C}$ unless stated otherwise

| Symbol | Parameter | Test Conditions | Min | Typ. | Max | Units |
|---------------------|--------------------------------|--|--|------|-----|-------|
| $t_{d(\text{off})}$ | Turn-off delay time | $I_C = 400\text{A}$ $V_{GE} = \pm 15\text{V}$ $V_{CE} = 1800\text{V}$ $R_{G(\text{ON})} = 8.2\ \Omega$ $R_{G(\text{OFF})} = 5.6\ \Omega$ $C_{ge} = 110\text{nF}$ $L_S \sim 100\text{nH}$ | | 2100 | | ns |
| t_f | Fall time | | | 210 | | ns |
| E_{OFF} | Turn-off energy loss | | | 520 | | mJ |
| $t_{d(\text{on})}$ | Turn-on delay time | | | 1130 | | ns |
| t_r | Rise time | | | 245 | | ns |
| E_{ON} | Turn-on energy loss | | | 620 | | mJ |
| Q_{rr} | Diode reverse recovery charge | | $I_F = 400\text{A}$ $V_{CE} = 1800\text{V}$ $di_F/dt = 2000\text{A}/\mu\text{s}$ | | 160 | |
| I_{rr} | Diode reverse recovery current | | | 330 | | A |
| E_{rec} | Diode reverse recovery energy | | | 150 | | mJ |

$T_{\text{case}} = 125^{\circ}\text{C}$ unless stated otherwise

| Symbol | Parameter | Test Conditions | Min | Typ. | Max | Units |
|---------------------|--------------------------------|--|--|------|-----|-------|
| $t_{d(\text{off})}$ | Turn-off delay time | $I_C = 400\text{A}$ $V_{GE} = \pm 15\text{V}$ $V_{CE} = 1800\text{V}$ $R_{G(\text{ON})} = 8.2\ \Omega$ $R_{G(\text{OFF})} = 5.6\ \Omega$ $C_{ge} = 110\text{nF}$ $L_S \sim 100\text{nH}$ | | 2150 | | ns |
| t_f | Fall time | | | 220 | | ns |
| E_{OFF} | Turn-off energy loss | | | 600 | | mJ |
| $t_{d(\text{on})}$ | Turn-on delay time | | | 1160 | | ns |
| t_r | Rise time | | | 285 | | ns |
| E_{ON} | Turn-on energy loss | | | 870 | | mJ |
| Q_{rr} | Diode reverse recovery charge | | $I_F = 400\text{A}$ $V_{CE} = 1800\text{V}$ $di_F/dt = 2000\text{A}/\mu\text{s}$ | | 300 | |
| I_{rr} | Diode reverse recovery current | | | 400 | | A |
| E_{rec} | Diode reverse recovery energy | | | 300 | | mJ |

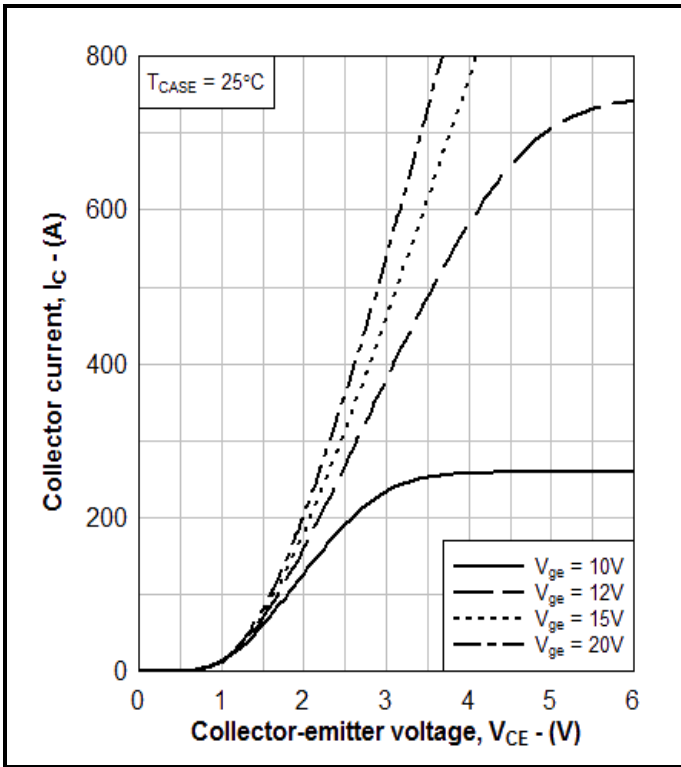


Fig. 3 Typical output characteristics

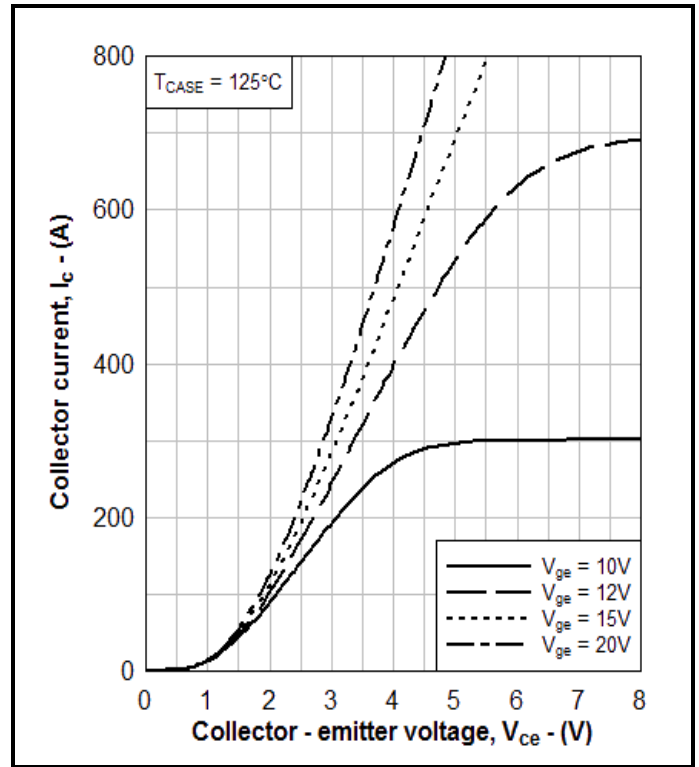


Fig. 4 Typical output characteristics

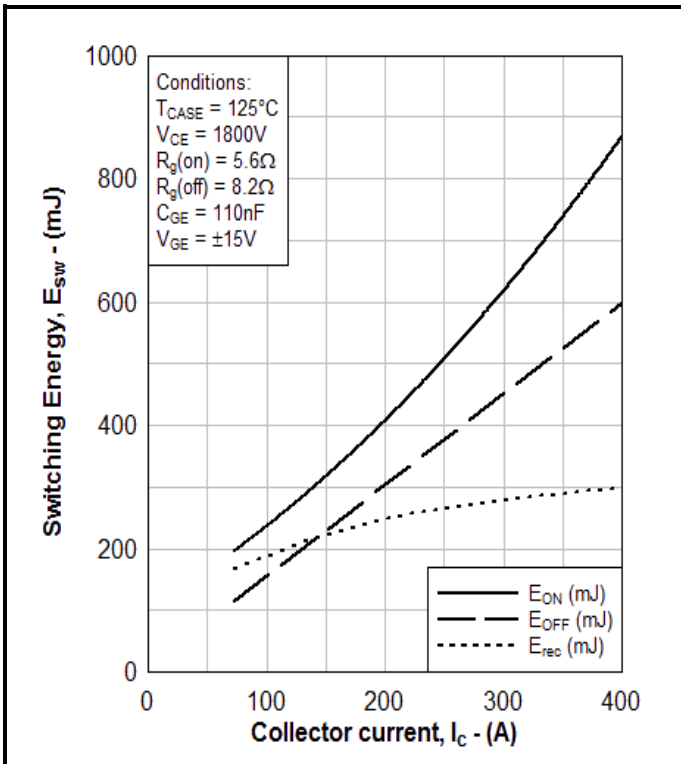


Fig. 5 Typical switching energy vs collector current

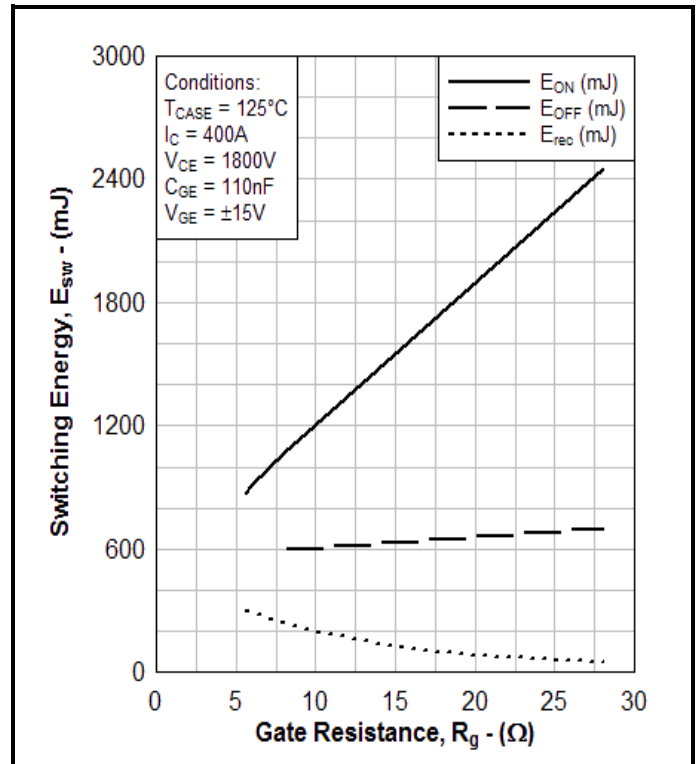


Fig. 6 Typical switching energy vs gate resistance

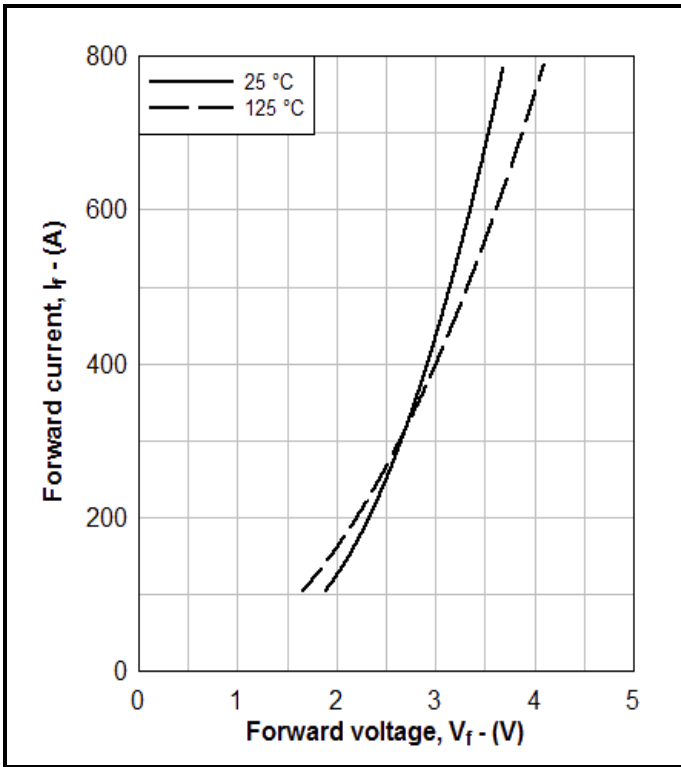


Fig. 7 Diode typical forward characteristics

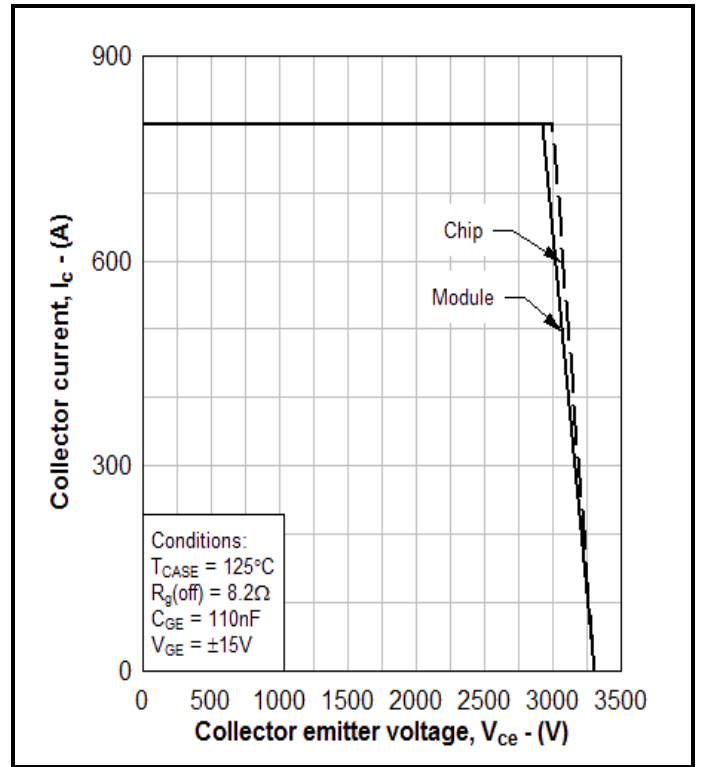


Fig. 8 Reverse bias safe operating area

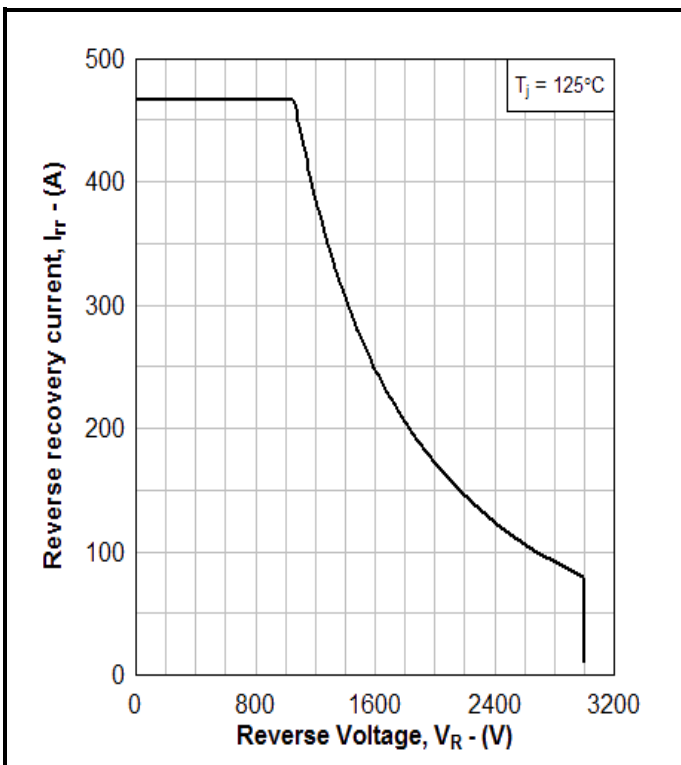


Fig. 9 Diode reverse bias safe operating area

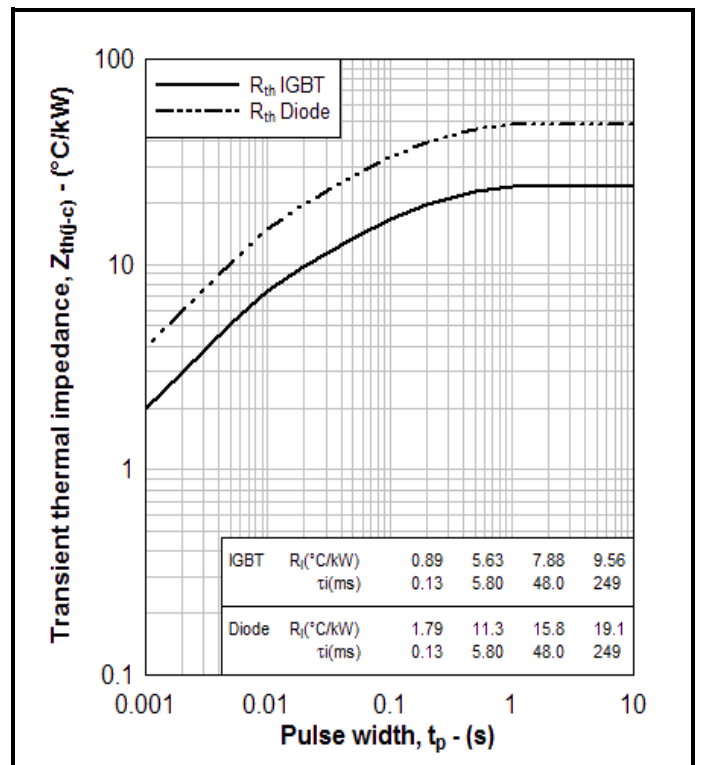
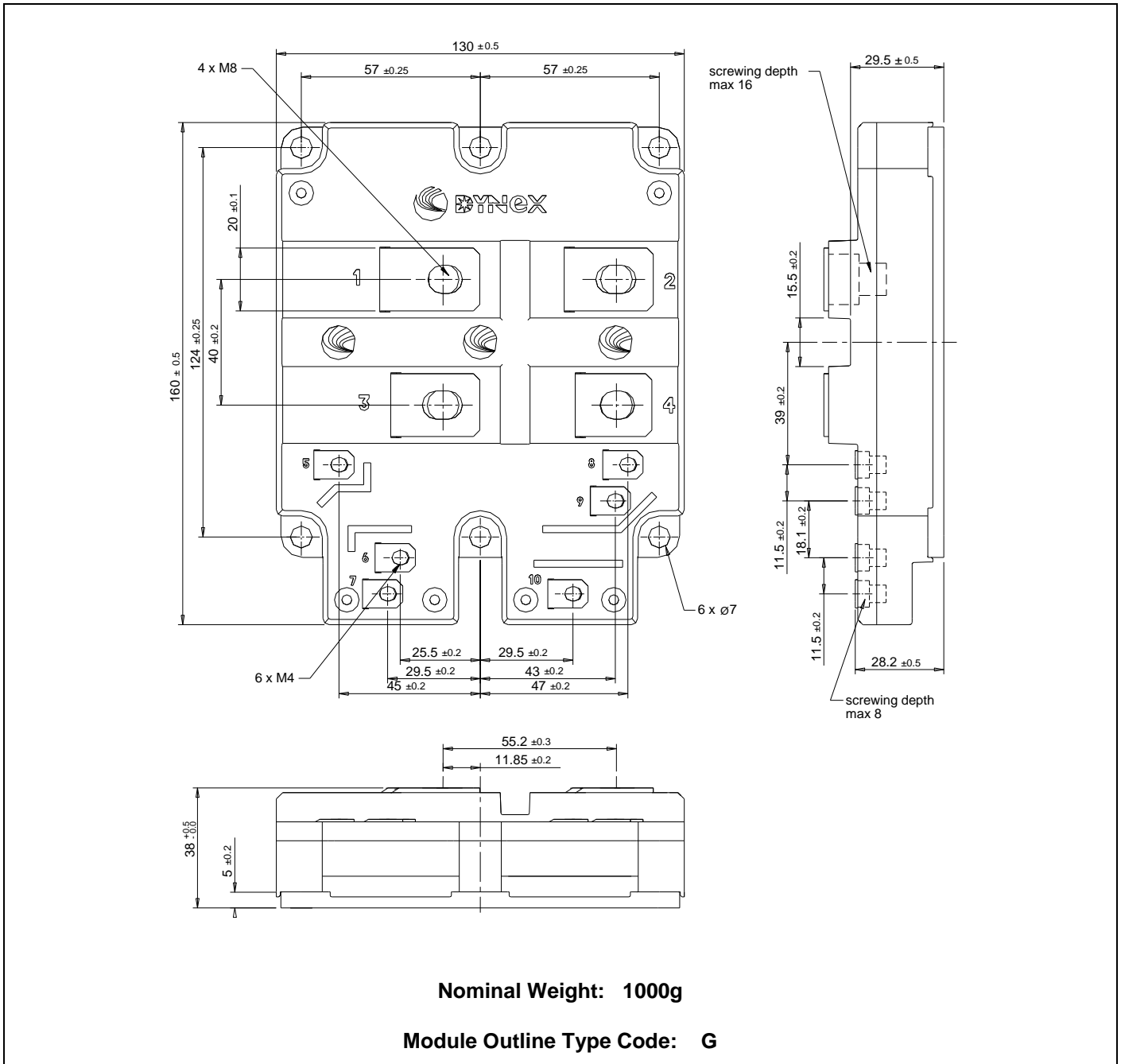


Fig. 10 Transient thermal impedance

PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services.
 All dimensions in mm, unless stated otherwise.
DO NOT SCALE.



Nominal Weight: 1000g

Module Outline Type Code: G

Fig. 11 Module outline drawing

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HEADQUARTERS OPERATIONS

DYNEX SEMICONDUCTOR LTD

Doddington Road, Lincoln, Lincolnshire, LN6 3LF,
United Kingdom

Fax: +44(0)1522 500550

Tel: +44(0)1522 500500

Web: <http://www.dynexsemi.com>

CUSTOMER SERVICE

DYNEX SEMICONDUCTOR LTD

Doddington Road, Lincoln, Lincolnshire, LN6 3LF,
United Kingdom

Fax: +44(0)1522 500020

Tel: +44(0)1522 502753 / 502901

Email: Power_solutions@dynexsemi.com